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APPLICATION NO.	FILIN	G DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/784,436	02/2	3/2004	William M. Hiatt	2269-5868US (01-0764.00/U	2546	
24247	7590	09/20/2006		EXAM	INER	
TRASK BRITT				SCHILLINGE	SCHILLINGER, LAURA M	
P.O. BOX 2550 SALT LAKE CITY, UT 84110				ART UNIT PAPER NUI		
SHET BINED CITT, CT CITT			2813			

Please find below and/or attached an Office communication concerning this application or proceeding.

	I A I'. d. Al						
	Application No.	Applicant(s)					
Office Assistant Commencer	10/784,436	WILLIAM HIATT					
Office Action Summary	Examiner	Art Unit					
	Laura M. Schillinger	2813					
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the c	orrespondence address					
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DA - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tim will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDONE	N. nely filed the mailing date of this communication. D (35 U.S.C. § 133).					
Status							
1) Responsive to communication(s) filed on 05 M	<u>ay 2006</u> .	•					
2a)⊠ This action is FINAL . 2b)☐ This							
3) Since this application is in condition for allowar	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is						
closed in accordance with the practice under E	Ex parte Quayle, 1935 C.D. 11, 45	53 O.G. 213.					
Disposition of Claims							
4)⊠ Claim(s) <u>1-9</u> is/are pending in the application.							
4a) Of the above claim(s) is/are withdraw	4a) Of the above claim(s) is/are withdrawn from consideration.						
5) Claim(s) is/are allowed.							
6)⊠ Claim(s) <u>1-9</u> is/are rejected.)⊠ Claim(s) <u>1-9</u> is/are rejected.						
7) Claim(s) is/are objected to.							
8) Claim(s) are subject to restriction and/or	r election requirement.						
Application Papers							
9) ☐ The specification is objected to by the Examine	r.						
10) The drawing(s) filed on is/are: a) acce	epted or b)⊡ objected to by the I	Examiner.					
Applicant may not request that any objection to the	drawing(s) be held in abeyance. See	e 37 CFR 1.85(a).					
Replacement drawing sheet(s) including the correct							
11)☐ The oath or declaration is objected to by the Ex	aminer. Note the attached Office	Action or form PTO-152.					
Priority under 35 U.S.C. § 119							
12) ☐ Acknowledgment is made of a claim for foreign a) ☐ All b) ☐ Some * c) ☐ None of:)-(d) or (f).					
1. Certified copies of the priority documents have been received.							
2. Certified copies of the priority documents	• •						
 Copies of the certified copies of the prior application from the International Bureau 		ed in this National Stage					
* See the attached detailed Office action for a list	• • • • • • • • • • • • • • • • • • • •	ed.					
		~ .					
Attachment(s)							
1) Notice of References Cited (PTO-892)	4) Interview Summary						
2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date Notice of Informal Patent Application							
Paper No(s)/Mail Date 6) Other:							

DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 1-8 are rejected under 35 U.S.C. 102(e) as being anticipated by Esashi et al ('465).

Esashi teaches the following claimed limitations as cited below:

1. (Original) A method for electrically coupling a first side of a semiconductor substrate to a second side of said semiconductor substrate, comprising:

forming a hole having an inner surface from a first side of a semiconductor substrate to a second side of said semiconductor substrate (Fig.8E (11D)); and

plating said inner surface of said semiconductor substrate to form a plated conductive element by forcing a plating solution from said first side of said semiconductor substrate to said second side of said semiconductor substrate through said hole (Fig.8H (12)).

2. (Original) The method of claim 1, wherein forming said hole comprises at least one of ablating, mechanically drilling and chemically etching a portion of said semiconductor substrate from said first side to said second side (Col.8, lines: 45-55).

- 3. (Original) The method of claim 1, further comprising loading said semiconductor substrate into a plating fixture, said semiconductor substrate and said plating fixture cooperatively directing flow of a plating material through said hole of said semiconductor substrate (Co1.8 ,lines: 55-65).
- 4. (Original) The method of claim 1, wherein said plating comprises electroplating said inner surface of said semiconductor substrate defined by said hole (Col.8, lines: 55-65).
- 5. (Original) The method of claim 1, wherein said plating process comprises electroless plating said inner surface of said semiconductor substrate defined by said hole (Col.8, lines: 55-65).
- 6. The method of claim 1, further comprising forming a conductive cap on at least one end of said plated conductive element (Fig.8 (11E)).
- 7. (Original) The method of claim 1, further comprising etching one of said first and second sides of said substrate to expose at least one end portion of said plated conductive element (Fig.8G) (11E)).
- 8. (Original) The method of claim 7, further comprising forming a conductive cap over said at least one end portion of said plated conductive element (Fig.8G (11E)).

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claim 9 is rejected under 35 U.S.C. 103(a) as being unpatentable over Esashi et al ('465).

In reference to claim 9, Esashi teaches method of claim 1, however fails to specify wherein said hole is between approximately 50 microns and 700 microns in diameter. This claim is prima facie obvious without showing that the claimed ranges achieve unexpected results relative to the prior art range. In re Woodruff, 16 USPQ2d 1935, 1937 (Fed. Cir. 1990). See also In re Huang, 40 USPQ2d 1685, 1688(Fed. Cir. 1996)(claimed ranges of a result effective variable, which do not overlap the prior art ranges, are unpatentable unless they produce a new and unexpected result which is different in kind and not merely in degree from the results of the prior art). See also In re Boesch, 205 USPQ 215 (CCPA) (discovery of optimum value of result effective variable in known process is ordinarily within skill of art) and In re Aller, 105 USPQ 233 (CCPA 1955) (selection of optimum ranges within prior art general conditions is obvious).

Response to Arguments

Applicant's arguments filed 5/5/06 have been fully considered but they are not persuasive. Applicant argues that Esashi et al fails to teach Applicant's claim language because the hole shown in Fig.8H is covered by plate 11. However, this is not persuasive because the

hole shown in Fig.8H extends from one side of the semiconductor substrate and extends to the second side and the plating solution is forced to the second side of the substrate as described by Esashi. The inner surface is therefore plated. Nothing in Applicant's claim language precludes this interpretation. The fact that the end of the hole is covered by a plate is irrelevant to the anticipation of Applicant's claim.

Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Laura M. Schillinger whose telephone number is (571) 272-1697. The examiner can normally be reached on M-T, R-F 7:00-5:00.

Art Unit: 2813

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl W. Whitehead, Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Xaeua Mfeles

9/14/06

Primary Examiner Primary L...

Art Unit 2813